



## DOCUMENT CHANGE REQUEST

DCR number	1566	Changes required for:	General	Originator:	Steve Thacker
Date:	2024/02/12	Date sent:	2023/04/04	Organisation:	ESCC Executive Secretariat
Status:	IMPLEMENTED				

Title: Evaluation Test Programme for Integrated Circuits: Monolithic Microcircuits, Wire-bonded, Plastic

Number: 2269030 Issue: 1

Other documents affected:

25200-4, 9030-2

Page:

As per current spec issue above; see also below & attached

Paragraph:

See Below

Original wording:

As per current spec issue above

Proposed wording:

In ESCC 25200:

Changes to implement SAM reject criteria per current ESCC9030 Para. 8.6 (& ESCC226903 Para 6.6) in new Para. 7.7: see attached for details (with changes highlighted yellow):  
i.e. Para. 1.2, 2.1, new Para. 7.7

Additional:

ESCC9030 Para. 8.6 & ESCC2269030 Para. 6.6 are amended to remove these same additional reject criteria. see attached for details (with changes highlighted yellow)

Justification:

to move the additional reject criteria for plastic encapsulated ICs from ESCC 9030 & 2269030 to 25200 as required by the 9000P Working Group.

Attachments:

esc9030iss\_draft\_2a\_in\_review.docx, esc25200iss\_draft\_4a\_in\_review.docx, esc2269030iss\_draft\_2a\_in\_review.docx

Modifications:

§7.1 has a typo. It writes "relative chances of the delamination area of more than 10%..." but it actually means "relative changes".

Approval signature:

A handwritten signature in black ink, appearing to be "SJD", is written in the signature box.

Date signed:

2024-02-12